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EFFECTIVE DATE:	08/10/2007

CONVEYING PARTY DATA

Name	Execution Date
The Regents of the University of California	07/27/2007

RECEIVING PARTY DATA

Name:	Japan Science and Technology Agency
Street Address:	4-1-8, Honcho
City:	Kawaguchi City, Saitama Prefecture
State/Country:	JAPAN
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PROPERTY NUMBERS Total: 2

Property Type	Number	
Application Number:	11403288	
PCT Number:	US0614084	

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NAME OF SUBMITTER: George H. Gates

Total Attachments: 1

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PATENT

REEL: 019681 FRAME: 0450

<u>ASSIGNMENT</u>

U.C. Case No. 2005-509-2

G & C Case No. 30794.132-WO/US-U1

For good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR, THE REGENTS OF THE UNIVERSITY OF CALIFORNIA, hereby sells, assigns and transfers to ASSIGNEE, JAPAN SCIENCE AND TECHNOLOGY AGENCY, a statutory corporation of the Japanese government, having its principal offices located at 4-1-8, Honcho, Kawaguchi City, Saitama Prefecture, 332-0012, Japan, and the successors, assigns and legal representatives of the ASSIGNEE, an undivided one-half (1/2) or fifty percent (50%) interest in and to the following patent applications:

PCT patent application no. PCT/US2006/014084, filed on April 13, 2006, by James S. Speck, Benjamin A. Haskell, P. Morgan Pattison and Troy J. Baker, and entitled ETCHING TECHNIQUE FOR THE FABRICATION OF THIN (AI, In, Ga)N LAYERS;

U.S. patent application serial no. 11/403,288, filed on April 13, 2006, by James S. Speck, Benjamin A. Haskell, P. Morgan Pattison and Troy J. Baker, and entitled ETCHING TECHNIQUE FOR THE FABRICATION OF THIN (AI, In, Ga)N LAYERS;

and any legal equivalent thereof in any country, including the right to claim priority and, in and to, all Letters Patent to be obtained therefor, and any continuation, division, continuation-in-part, extension, conversion to 35 U.S.C. §111(a) or substitute thereof, and any reissue, reexamination or extension of said Letters Patent and all rights under all International Conventions for the Protection of Industrial Property;

Executed this 27 day of July, 2007.

Signed: Auda & Heverson

Title: Manager, Patent Prosecution University of California

Office of Technology Transfer

assign.doc

RECORDED: 08/10/2007

PATENT REEL: 019681 FRAME: 0451